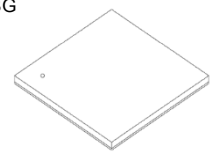
CMOS Digital Integrated Circuit Silicon Monolithic

TC358771XBG/TC358772XBG

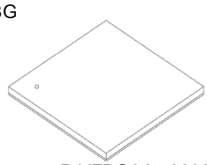
Mobile Peripheral Devices

TC358771XBG



P-VFBGA49-0505-0.65-001
Weight: 31 mg (Typ.)

TC358772XBG



P-VFBGA64-0606-0.65-001
Weight: 47mg (Typ.)

Overview

The TC358771XBG/TC358772XBG Functional Specification adds back light engine to function of TC358775XBG.
TC358771XBG/TC358772XBG is the follow-up chip of TC358774XBG/TC358775XBG, which:

1. Is pin compatible to TC358774XBG/TC358775XBG
2. Exhibit LVDS Tx block operates at 1.8V @135 MHz to reduce operation power
3. Back light engine controls the back light level automatically with ambient light and adjusts image contents.

The primary function of this chip is DSI-to-LVDS Bridge, enabling video streaming output over DSI link to drive LVDS-compatible display panels. The chip supports up to 1600x1200 24-bit pixel resolution for single-link LVDS and up to WUXGA (1920x1200 24-bit pixels) resolution for dual-link LVDS. As a secondary function, the chip also supports an I^2C Master which is controlled by the DSI link; this may be used as an interface to any other control functions through I^2C.

Features

● DSI Receiver

- ✧ Configurable 1- up to 4-Data-Lane DSI Link with bi-directional support on Data Lane 0
- ✧ Maximum bit rate of 1 Gbps/lane
- ✧ Video input data formats:
  - RGB565 16 bits per pixel
  - RGB666 18 bits per pixel
  - RGB666 loosely packed 24 bits per pixel
  - RGB888 24 bits per pixel
- ✧ Video frame size:
  - Up to 1600×1200 24-bit/pixel resolution to single-link LVDS display panel, limited by 135 MHz LVDS speed
  - Up to WUXGA resolutions (1920×1200 24-bit pixels) to dual-link LVDS display panel, limited by 4 Gbps DSI link speed
- ✧ Supports Video Stream packets for video data transmission.
- ✧ Supports generic long packets for accessing the chip's register set
- ✧ Supports the path for Host to control the on-chip I^2C Master

● LVDS FPD Link Transmitter

- ✧ Supports single-link or dual-link
- ✧ Maximum pixel clock frequency of 135 MHz.
- ✧ Supports display up to 1600×1200 24-bit/pixel resolution for single-link, or up to 1920×1200 24-bit resolutions for dual-link
- ✧ Supports the following pixel formats:
  - RGB666 18 bits per pixel
  - RGB888 24 bits per pixel
- ✧ Features Toshiba Magic Square algorithm which enables a RGB666 display panel to produce a display quality almost equivalent to that of an RGB888 24-bit panel
- ✧ Flexible mapping of parallel data input bit ordering
- ✧ Supports programmable clock polarity
- ✧ Supports two power saving states
  - Sleep state, when receiving DSI ULPS signaling
  - Standby state, entered by STBY pin assertion

● Back Light Engine

- ✧ Provides a proper backlight parameter to the environment light

● System Operation

- ✧ Host configures the chip through DSI link
- ✧ Through DSI link, Host accesses the chip register set using Generic Write and Read packets. One Generic Long Write packet can write to multiple contiguous register addresses
- ✧ Includes an I^2C Master function which is controlled by Host through DSI link (multi-master is not supported)
- ✧ Power management features to save power
- ✧ Configuration registers is also accessible through I^2C Slave interface

- **Clock Source**
  - ✧ LVDS pixel clock source is either from external clock EXTCLK or derived from DSICLK.
  - ✧ A built-in PLL generates the high-speed LVDS serializing clock requiring no external components
- **Digital Input/Output Signals**
  - ✧ All Digital Input signals are 3.3V tolerant
  - ✧ All Digital Output signals can output ranging from 1.8V to 3.3V depending on IO supply voltage
- **Power supply**
  - ✧ MIPI DSI D-PHY: 1.2 V
  - ✧ LVDS PHY: 1.8 V
  - ✧ I/O: 1.8 V - 3.3V (all IO supply pins must be same level)
  - ✧ Digital Core: 1.2 V
- **Power Consumption (Typical Condition)**
  - ✧ Evaluation image data: color bar
  - ✧ Power Down State is achieved by:
    1. Reset asserted
    2. EXTCLK not toggling
    3. STBY = 0
    4. DSI in ULPS Drive
- **Packaging Information**
  - ✧ BGA64 (0.65mm ball pitch)
    - Supports DSI-RX 4-data-lanes + Dual-Link LVDS-TX
    - 6.0mm × 6.0mm × 1.0mm
  - ✧ BGA49 (0.65mm ball pitch)
    - Supports DSI-RX 4-data-lanes + Single-Link LVDS-TX
    - 5.0mm × 5.0mm × 1.0mm

Table of contents

List of Figures

List of Tables

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This Notice of Disclaimer applies to all DSI input and processing paths related descriptions throughout this document.

REFERENCE

1. MIPI D-PHY, “MIPI_D-PHY_specification_v01-00-00, May 14, 2009"
2. MIPI Alliance Specification for DSI version 1.01, Feb 2008
3. MIPI Alliance Specification for DPI version 2.0, Sep, 2005
4. An Introduction to FPD-Link, AN-1032, Application Note, National Semiconductor 2009
5. DS90C383/DS90CF384 LVDS Transmitter 24-Bit FPD Link, Data Sheet, National Semiconductor 2000
6. THC63LVD823 Single/Dual Link LVDS Transmitter, Data Sheet, Thine Electronics, 2000-2003.
7. SN75LVDS83 FlatLink Transmitter, Data Sheet, Texas Instrument, 1997-2009.

Precautions and Usage Considerations Specific to Application Specific Standard Products and General-Purpose Linear Ics

Design

⚠ CAUTION

Use an appropriate power supply fuse to ensure that a large current does not continuously flow in case of over current and/or IC failure. The IC will fully break down when used under conditions that exceed its absolute maximum ratings, when the wiring is routed improperly or when an abnormal pulse noise occurs from the wiring or load, causing a large current to continuously flow and the breakdown can lead smoke or ignition. To minimize the effects of the flow of a large current in case of breakdown, appropriate settings, such as fuse capacity, fusing time and insertion circuit location, are required.

If your design includes an inductive load such as a motor coil, incorporate a protection circuit into the design to prevent device malfunction or breakdown caused by the current resulting from the inrush current at power ON or the negative current resulting from the back electromotive force at power OFF. For details on how to connect a protection circuit such as a current limiting resistor or back electromotive force adsorption diode, refer to individual IC datasheets or the IC databook. IC breakdown may cause injury, smoke or ignition.

Use a stable power supply with ICs with built-in protection functions. If the power supply is unstable, the protection function may not operate, causing IC breakdown. IC breakdown may cause injury, smoke or ignition.

Carefully select external components (such as inputs and negative feedback capacitors) and load components (such as speakers), for example, power amp and regulator.
If there is a large amount of leakage current such as input or negative feedback condenser, the IC output DC voltage will increase. If this output voltage is connected to a speaker with low input withstand voltage, overcurrent or IC failure can cause smoke or ignition. (The over current can cause smoke or ignition from the IC itself.) In particular, please pay attention when using a Bridge Tied Load (BTL) connection type IC that inputs output DC voltage to a speaker directly.

Over current Protection Circuit

Over current protection circuits (referred to as current limiter circuits) do not necessarily protect ICs under all circumstances. If the Over current protection circuits operate against the over current, clear the over current status immediately.
Depending on the method of use and usage conditions, such as exceeding absolute maximum ratings can cause the over current protection circuit to not operate properly or IC breakdown before operation. In addition, depending on the method of use and usage conditions, if over current continues to flow for a long time after operation, the IC may generate heat resulting in breakdown.

Thermal Shutdown Circuit

Thermal shutdown circuits do not necessarily protect ICs under all circumstances. If the Thermal shutdown circuits operate against the over temperature, clear the heat generation status immediately.
Depending on the method of use and usage conditions, such as exceeding absolute maximum ratings can cause the thermal shutdown circuit to not operate properly or IC breakdown before operation.

Heat Radiation Design

When using an IC with large current flow such as power amp, regulator or driver, please design the device so that heat is appropriately radiated, not to exceed the specified junction temperature (T_J) at any time and condition. These ICs generate heat even during normal use. An inadequate IC heat radiation design can lead to decrease in IC life, deterioration of IC characteristics or IC breakdown. In addition, please design the device taking into considerate the effect of IC heat radiation with peripheral components.

Mounting

Installation to Heat Sink

Please install the power IC to the heat sink not to apply excessive mechanical stress to the IC. Excessive mechanical stress can lead to package cracks, resulting in a reduction in reliability or breakdown of internal IC chip. In addition, depending on the IC, the use of silicon rubber may be prohibited. Check whether the use of silicon rubber is prohibited for the IC you intend to use, or not. For details of power IC heat radiation design and heat sink installation, refer to individual technical datasheets or IC databooks.

Also please refer to ”RESTRICTIONS ON PRODUCT USE”.

1. Introduction

The TC358771XBG/TC358772XBG Functional Specification adds back light engine to function of 775XBG. TC358771XBG/TC358772XBG is the follow-up chip of TC358774XBG/TC358775XBG, which:

1. Is pin compatible to TC358774XBG/TC358775XBG
2. Exhibit LVDS Tx block operates at 1.8V @135 MHz to reduce operation power
3. Back light engine controls the back light level automatically with ambient light and adjusts image contents.

The primary function of this chip is DSI-to-LVDS Bridge, enabling video streaming output over DSI link to drive LVDS-compatible display panels. The chip supports up to 1600×1200 24-bit pixel resolution for single-link LVDS and up to WUXGA (1920×1200 24-bit pixels) resolution for dual-link LVDS. As a secondary function, the chip also supports an I^2C Master which is controlled by the DSI link; this may be used as an interface to any other control functions through I^2C.

The chip can be configured through the DSI link by sending write register commands through DSI Generic Long Write-packets. It can also be configured through the I^2C Slave interface. I^2C slave address of TC358771XBG/TC358772XBG is 8'b0001_111X, where X = 0/1 for write/read to/from TC358771XBG/TC358772XBG operation.

This specification provides description of two product versions:

TC358771XBG-49: In BGA49 package, it supports DSI-RX with up to 4 data lanes, and outputs to Single-Link LVDS.

TC358772XBG-64: In BGA64 package, it supports DSI-RX with up to 4 data lanes, and outputs to Single-Link and Dual-Link LVDS.

1.1. Scope

This document details the operation of the chip, description of each major function that the chip supports, description of the configuration register set, and includes pinout, package, and electrical characteristics information.

1.2. Purpose

This document serves as the vehicle for exchanging detailed technical information of the TC358771XBG/TC358772XBG and its usage within the target application systems at the customer side. It also serves as the chip functional specification for design implementation and verification.

2. Device Overview

The TC358771XBG/TC358772XBG chip functions primarily as a DSI-to-LVDS communication protocol bridge, enabling video streaming from a Host processor over DSI link to drive LVDS-compatible display panels. In other words, the chip receives video stream input through its DSI receiver (DSI-RX), buffers the received pixel data in a buffer, and then re-transmits the video stream out through the LVDS transmitter.

As a secondary function, the chip also ports an I^2C Master which is controlled by the DSI link; this may be used as a programming interface to other peripherals in the system.

As a 3rd function, automatically control the back light level and adjust image contents based on ambient light.

The chip is configured through the DSI link. Alternatively, it can optionally be configured through the I^2C Slave interface; in such case, the I^2C Master function would be disabled.

The reference video pixel clock for the LVDS link is sourced either from an external clock via input pin EXTCLK or derived from DSICLK. The chip integrates a PLL which synthesizes the high-speed clock for use solely to serialize video data over the LVDS link.

The DSI-RX receiver supports from 1- to 4-Lane configurations at bit rate up to 1 Gbps per lane. Host can transmit video in video mode. In video mode, Host controls video timing by sending video frame and line sync events together with video pixel data; video data transmission can be burst or non-burst. Since the chip integrates only 1024-pixel of video buffer, Host still has to take care of transmitting pixel data at appropriate video line time in order to avoid buffer overflow (or underflow).

The LVDS transmitter supports a clock frequency of up to 135 MHz for either single- or dual-link.

The chip supports power management to conserve power when its functions are not in use. Host manages the chip's power consumption states by using ULPS signaling over DSI link and/or STBY pin.

3. Features

- **DSI Receiver**
  - ✧ Configurable 1- up to 4-Data-Lane DSI Link with bi-directional support on Data Lane 0
  - ✧ Maximum bit rate of 1 Gbps/lane
  - ✧ Video input data formats:
    - RGB565 16 bits per pixel
    - RGB666 18 bits per pixel
    - RGB666 loosely packed 24 bits per pixel
    - RGB888 24 bits per pixel.
  - ✧ Video frame size:
    - Up to 1600x1200 24-bit/pixel resolution to single-link LVDS display panel, limited by 135 MHz LVDS speed
    - Up to WUXGA resolutions (1920x1200 24-bit pixels) to dual-link LVDS display panel, limited by 4 Gbps DSI link speed
  - ✧ Supports Video Stream packets for video data transmission.
  - ✧ Supports generic long packets for accessing the chip's register set
  - ✧ Supports the path for Host to control the on-chip I^2C Master

- **LVDS FPD Link Transmitter**
  - ✧ Supports single-link or dual-link
  - ✧ Maximum pixel clock frequency of 135 MHz.
  - ✧ Supports display up to 1600×1200 24-bit/pixel resolution for single-link, or up to 1920×1200 24-bit resolutions for dual-link
  - ✧ Supports the following pixel formats:
    - RGB666 18 bits per pixel
    - RGB888 24 bits per pixel
  - ✧ Features Toshiba Magic Square algorithm which enables a RGB666 display panel to produce a display quality almost equivalent to that of an RGB888 24-bit panel
  - ✧ Flexible mapping of parallel data input bit ordering
  - ✧ Supports programmable clock polarity
  - ✧ Supports two power saving states
    - Sleep state, when receiving DSI ULPS signaling
    - Standby state, entered by STBY pin assertion

- **Back Light Engine**
  - ✧ Provides a proper backlight parameter to the environment light

- **System Operation**
  - ✧ Host configures the chip through DSI link
  - ✧ Through DSI link, Host accesses the chip register set using Generic Write and Read packets. One Generic Long Write packet can write to multiple contiguous register addresses
  - ✧ Includes an I^2C Master function which is controlled by Host through DSI link (multi-master is not supported)
  - ✧ Power management features to save power
  - ✧ Configuration registers is also accessible through I^2C Slave interface

- **Clock Source**
  - ✧ LVDS pixel clock source is either from external clock EXTCLK or derived from DSICLK.
  - ✧ A built-in PLL generates the high-speed LVDS serializing clock requiring no external components

- **Digital Input/Output Signals**
  - ✧ All Digital Input signals are 3.3V tolerant
  - ✧ All Digital Output signals can output ranging from 1.8V to 3.3V depending on IO supply voltage

- **Power supply**
  - ✧ MIPI DSI D-PHY: 1.2 V
  - ✧ LVDS PHY: 1.8 V
  - ✧ I/O: 1.8 V - 3.3V (all IO supply pins must be same level)
  - ✧ Digital Core: 1.2 V

- **Power Consumption (Typical Condition)**
  - ✧ Evaluation image data : color bar
  - ✧ Power Down State is achieved by:
    1. Reset asserted
    2. EXTCLK not toggling
    3. STBY=0
    4. DSI in ULPS Drive

Normal Mode									
	Condition		VDDC	VDDS	DSI	LVDS		TOTAL Power	Unit
	LVDS	DSI	VDDC	VDDIO	VDDMIPI	LVDS12	LVDS18		
			1.2	3.3	1.2	1.2	1.8		V
1280x800x18 @60fps	75MHz	300MHz	29.6	0.08	13.6	7.4	16.1		mA
	Single link	4Lane	35.52	0.26	16.32	8.88	28.98	89.96	mW
1920x1080x18 @60fps	75MHz	450MHz	55.2	0.08	16.8	8.3	32.10		mA
	Dual link	4Lane	66.24	0.26	20.16	10.08	57.78	154.40	mW
Power Down	-	-	0.4	0.001	0.1	0.1	0.001		mA
	-	-	0.48	0.0033	0.12	0.12	0.0018	0.73	mW

- **Packaging Information**
  - ✧ BGA64 (0.65mm ball pitch)
    - Supports DSI-RX 4-data-lanes + Dual-Link LVDS-TX
    - 6.0mm × 6.0mm × 1.0mm
  - ✧ BGA49 (0.65mm ball pitch)
    - Supports DSI-RX 4-data-lanes + Single-Link LVDS-TX
    - 5.0mm × 5.0mm × 1.0mm

4. Pin Layout

A1	A2	A3	A4	A5	A6	A7	A8
VSS_LVDS2_12	LVTX2AN	LVTX2BN	LVTX2CN	LVTX2DN	LVTX2EN	VSS_LVDS2_18	VSS_LVDS1_12
B1	B2	B3	B4	B5	B6	B7	B8
VDD_LVDS2_12	LVTX2AP	LVTX2BP	LVTX2CP	LVTX2DP	LVTX2EP	VDD_LVDS2_18	VDD_LVDS1_12
C1	C2	C3	C4	C5	C6	C7	C8
VSSIO	VDDIO	STBY	PWMO	VDD_LVDS2_18	VSS_LVDS2_18	LVTX1AP	LVTX1AN
D1	D2	D3	D4	D5	D6	D7	D8
EXTCLK	GPIO2	GPIO1	RESX	TM	VDD_LVDS1_18	LVTX1BP	LVTX1BN
E1	E2	E3	E4	E5	E6	E7	E8
VSSC	VDDC	GPIO0	VDDC	VSSC	VSS_LVDS1_18	LVTX1CP	LVTX1CN
F1	F2	F3	F4	F5	F6	F7	F8
VSSIO	VDDIO	VDD_MIPI	VSS_MIPI	VSS_MIPI	VDD_MIPI	LVTX1DP	LVTX1DN
G1	G2	G3	G4	G5	G6	G7	G8
I2C_SCL	DSRXD0P	DSRXD1P	DSRXCP	DSRXD2P	DSRXD3P	LVTX1EP	LVTX1EN
H1	H2	H3	H4	H5	H6	H7	H8
I2C_SDA	DSRXD0M	DSRXD1M	DSRXCM	DSRXD2M	DSRXD3M	VDD_LVDS1_18	VSS_LVDS1_18

Figure 4.1 TC358772XBG Pin Layout (BGA64 – Top View)

A1	A2	A3	A4	A5	A6	A7
VSSIO	VDDIO	RESX	GPIO0	VSSC	VDDC	VSSC
B1	B2	B3	B4	B5	B6	B7
EXTCLK	VDDC	VSSC	TM	VDD_LVDS1_12	LVTX1AP	LVTX1AN
C1	C2	C3	C4	C5	C6	C7
I2C_SDA	PWMO	GPIO2	GPIO1	VSS_LVDS1_12	LVTX1BP	LVTX1BN
D1	D2	D3	D4	D5	D6	D7
I2C_SCL	STBY	VSS_MIPI	VDD_MIPI	VSS_LVDS1_18	LVTX1CP	LVTX1CN
E1	E2	E3	E4	E5	E6	E7
VDDIO	VSSIO	VSS_MIPI	VDD_MIPI	VDD_LVDS1_18	LVTX1DP	LVTX1DN
F1	F2	F3	F4	F5	F6	F7
DSRXD0P	DSRXD1P	DSRXCP	DSRXD2P	DSRXD3P	LVTX1EP	LVTX1EN
G1	G2	G3	G4	G5	G6	G7
DSRXD0M	DSRXD1M	DSRXCM	DSRXD2M	DSRXD3M	VDD_LVDS1_18	VSS_LVDS1_18

Figure 4.2 TC358771XBG Chip Pin Layout (BGA49 – Top View)

4.1. TC358772XBG BGA64 Pin-out Description

Group	Pin Name	IO Type	Pin Cnt.	Description	State of pin at reset active	Power Supply Voltage
DSI-RX IF	DSRXCP	DSI-PHY	1	DSI clock signal - positive	Hi-z	1.2 V
	DSRXCM	DSI-PHY	1	DSI clock signal - negative	Hi-z	1.2 V
	DSRXD0P	DSI-PHY	1	DSI data lane 0 - positive	Hi-z	1.2 V
	DSRXD0M	DSI-PHY	1	DSI data lane 0 - negative	Hi-z	1.2 V
	DSRXD1P	DSI-PHY	1	DSI data lane 1 - positive	Hi-z	1.2 V
	DSRXD1M	DSI-PHY	1	DSI data lane 1 - negative	Hi-z	1.2 V
	DSRXD2P	DSI-PHY	1	DSI data lane 2 - positive	Hi-z	1.2 V
	DSRXD2M	DSI-PHY	1	DSI data lane 2 - negative	Hi-z	1.2 V
	DSRXD3P	DSI-PHY	1	DSI data lane 3 - positive	Hi-z	1.2 V
	DSRXD3M	DSI-PHY	1	DSI data lane 3 – negative	Hi-z	1.2 V
	VDD_MIPI	Power	2	MIPI Analog Power Supply	-	1.2 V
	VSS_MIPI	Ground	2	MIPI Analog Ground	-	GND
1st-Link LVDS-TX IF	LVTX1AP	LVDS-PHY	1	LVDS first-link data channel A - positive	Hi-z	1.8 V
	LVTX1AN	LVDS-PHY	1	LVDS first-link data channel A - negative	Hi-z	1.8 V
	LVTX1BP	LVDS-PHY	1	LVDS first-link data channel B - positive	Hi-z	1.8 V
	LVTX1BN	LVDS-PHY	1	LVDS first-link data channel B - negative	Hi-z	1.8 V
	LVTX1CP	LVDS-PHY	1	LVDS first-link data channel C - positive	Hi-z	1.8 V
	LVTX1CN	LVDS-PHY	1	LVDS first-link data channel C - negative	Hi-z	1.8 V
	LVTX1DP	LVDS-PHY	1	LVDS first-link data channel D (Clock) - positive	Hi-z	1.8 V
	LVTX1DN	LVDS-PHY	1	LVDS first-link data channel D (Clock) - negative	Hi-z	1.8 V
	LVTX1EP	LVDS-PHY	1	LVDS first-link data channel E - positive	Hi-z	1.8 V
	LVTX1EN	LVDS-PHY	1	LVDS first-link data channel E – negative	Hi-z	1.8 V
	VDD_LVDS1_18	Power	2	First-link LVDS 1.8V Power Supply	-	1.8 V
	VSS_LVDS1_18	Ground	2	First-link LVDS 1.8V Ground	-	GND
	VDD_LVDS1_12	Power	1	First-link LVDS 1.2V Power Supply	-	1.2 V
	VSS_LVDS1_12	Ground	1	First-link LVDS 1.2V Ground	-	GND
2nd-Link LVDS-TX IF	LVTX2AP	LVDS-PHY	1	LVDS second-link data channel A - positive	Hi-z	1.8 V
	LVTX2AN	LVDS-PHY	1	LVDS second-link data channel A - negative	Hi-z	1.8 V
	LVTX2BP	LVDS-PHY	1	LVDS second-link data channel B - positive	Hi-z	1.8 V
	LVTX2BN	LVDS-PHY	1	LVDS second-link data channel B - negative	Hi-z	1.8 V
	LVTX2CP	LVDS-PHY	1	LVDS second-link data channel C - positive	Hi-z	1.8 V
	LVTX2CN	LVDS-PHY	1	LVDS second-link data channel C - negative	Hi-z	1.8 V
	LVTX2DP	LVDS-PHY	1	LVDS second-link data channel D (Clock) - positive	Hi-z	1.8 V
	LVTX2DN	LVDS-PHY	1	LVDS second-link data channel D (Clock) -negative	Hi-z	1.8 V
	LVTX2EP	LVDS-PHY	1	LVDS second-link data channel E - positive	Hi-z	1.8 V
	LVTX2EN	LVDS-PHY	1	LVDS second-link data channel E – negative	Hi-z	1.8 V
	VDD_LVDS2_18	Power	2	Second-link LVDS 1.8V Power Supply	-	1.8 V
	VSS_LVDS2_18	Ground	2	Second-link LVDS 1.8V Ground	-	GND
	VDD_LVDS2_12	Power	1	Second-link LVDS 1.2V Power Supply	-	1.2 V
	VSS_LVDS2_12	Ground	1	Second-link LVDS 1.2V Ground	-	GND
I^2C IF	I2C_SCL	S-OD	1	I^2C Master or Slave interface clock signal	Hi-z	1.8V-3.3V
	I2C_SDA	S-OD	1	I^2C Master or Slave interface data signal	Hi-z	1.8V-3.3V
GPIO	GPIO[2:0]	N_{PD}	3	GPIO bits 2-0	Hi-z	1.8V-3.3V
PWM	PWMO	N_{PD}	1	PWM Output / GPIO bit 3(Initial function)	Hi-z	1.8V-3.3V
SYSTEM	RESX	N_{PD}	1	Hardware reset, low active	Hi-z	1.8V-3.3V
	EXTCLK	N_{PD}	1	External pixel clock source	Hi-z	1.8V-3.3V
	STBY	N	1	Standby pin, low active	Hi-z	1.8V-3.3V
	TM	N_{PD}	1	Test mode select	Hi-z	1.8V-3.3V
	VDDIO	Power	2	IO Power Supply	-	1.8-3.3V
	VSSIO	Ground	2	IO Ground	-	GND
	VDDC	Power	2	Digital Core Power Supply	-	1.2 V
	VSSC	Ground	2	Digital Core Ground	-	GND

Buffer Type Abbreviation:

N:	Normal IO
N_{PD}:	Normal IO with weak Internal Pull-Down
N_{PU}:	Normal IO with weak Internal Pull-Up
S-OD:	Pseudo open-drain output, schmitt trigger input
SCHMIDTT:	Fail Safe schmitt trigger input buffer
DSI-PHY:	front-end analog IO for DSI
LVDS-PHY:	front-end analog IO for LVDS
A:	Analog pad

4.2. TC358772XBG BGA64 Pin Count Summary

Table 4.1 TC358772XBG BGA64 Pin Count Summary

Group Name	Pin Count	Notes
DSI-RX IF	14	Include DSI Power & Ground
1st-Link LVDS-TX IF/ 2nd-Link LVDS-TX IF	32	Include LVDS Power & Ground
I^2C IF	2	-
GPIO	3	-
PWM	1	-
SYSTEM	12	Include Power & Ground
Total Pin Count	**64**	

4.3. TC358771XBG BGA49 Pin-out Description

Group	Pin Name	IO Type	Pin Cnt.	Description	State of pin at reset active	Power Supply Voltage
DSI-RX IF	DSRXCP	DSI-PHY	1	DSI clock signal - positive	Hi-z	DSICP
	DSRXCM	DSI-PHY	1	DSI clock signal - negative	Hi-z	DSICM
	DSRXD0P	DSI-PHY	1	DSI data lane 0 - positive	Hi-z	1.2 V
	DSRXD0M	DSI-PHY	1	DSI data lane 0 - negative	Hi-z	1.2 V
	DSRXD1P	DSI-PHY	1	DSI data lane 1 - positive	Hi-z	1.2 V
	DSRXD1M	DSI-PHY	1	DSI data lane 1 - negative	Hi-z	1.2 V
	DSRXD2P	DSI-PHY	1	DSI data lane 2 - positive	Hi-z	1.2 V
	DSRXD2M	DSI-PHY	1	DSI data lane 2 - negative	Hi-z	1.2 V
	DSRXD3P	DSI-PHY	1	DSI data lane 3 - positive	Hi-z	1.2 V
	DSRXD3M	DSI-PHY	1	DSI data lane 3 – negative	Hi-z	1.2 V
	VDD_MIPI	Power	2	MIPI Analog Power Supply	-	1.2 V
	VSS_MIPI	Ground	2	MIPI Analog Ground	-	GND
LVDS-TX IF	LVTX1AP	LVDS-PHY	1	LVDS first-link data channel A - positive	Hi-z	1.8 V
	LVTX1AN	LVDS-PHY	1	LVDS first-link data channel A - negative	Hi-z	1.8 V
	LVTX1BP	LVDS-PHY	1	LVDS first-link data channel B - positive	Hi-z	1.8 V
	LVTX1BN	LVDS-PHY	1	LVDS first-link data channel B - negative	Hi-z	1.8 V
	LVTX1CP	LVDS-PHY	1	LVDS first-link data channel C - positive	Hi-z	1.8 V
	LVTX1CN	LVDS-PHY	1	LVDS first-link data channel C - negative	Hi-z	1.8 V
	LVTX1DP	LVDS-PHY	1	LVDS first-link data channel D (Clock) - positive	Hi-z	1.8 V
	LVTX1DN	LVDS-PHY	1	LVDS first-link data channel D (Clock) - negative	Hi-z	1.8 V
	LVTX1EP	LVDS-PHY	1	LVDS first-link data channel E - positive	Hi-z	1.8 V
	LVTX1EN	LVDS-PHY	1	LVDS first-link data channel E – negative	Hi-z	1.8 V
	VDD_LVDS1_18	Power	2	First-link LVDS 1.8V Power Supply	-	1.8 V
	VSS_LVDS1_18	Ground	2	First-link LVDS 1.8V Ground	-	GND
	VDD_LVDS1_12	Power	1	First-link LVDS 1.2V Power Supply	-	1.2 V
	VSS_LVDS1_12	Ground	1	First-link LVDS 1.2V Ground	-	GND
I^2C IF	I2C_SCL	S-OD	1	I^2C Master or Slave interface clock signal	Hi-z	1.8V-3.3V
	I2C_SDA	S-OD	1	I^2C Master or Slave interface data signal	Hi-z	1.8V-3.3V
GPIO	GPIO[3:0]	N_{PD}	4	GPIO bits 2-0	Hi-z	1.8V-3.3V
PWM	PWMO	N_{PD}	1	PWM Output / GPIO bit 3(Initial Function)	Hi-z	1.8V-3.3V
SYSTEM	RESX	N_{PD}	1	Hardware reset, low active	Hi-z	1.8V-3.3V
	EXTCLK	N_{PD}	1	External pixel clock source	Hi-z	1.8V-3.3V
	STBY	N	1	Standby pin, low active	Hi-z	1.8V-3.3V
	TM	N_{PD}	1	Test mode select	Hi-z	1.8V-3.3V
	VDDIO	Power	2	IO Power Supply	-	1.8-3.3V
	VSSIO	Ground	2	IO Ground	-	GND
	VDDC	Power	2	Digital Core Power Supply	-	1.2 V
	VSSC	Ground	3	Digital Core Ground	-	GND

Buffer Type Abbreviation:

N: Normal IO
S-OD: Pseudo open-drain output, schmitt trigger input
SCHMIDTT: Fail Safe schmitt trigger input buffer
DSI-PHY: front-end analog IO for DSI
LVDS-PHY: front-end analog IO for LVDS
A: Analog pad

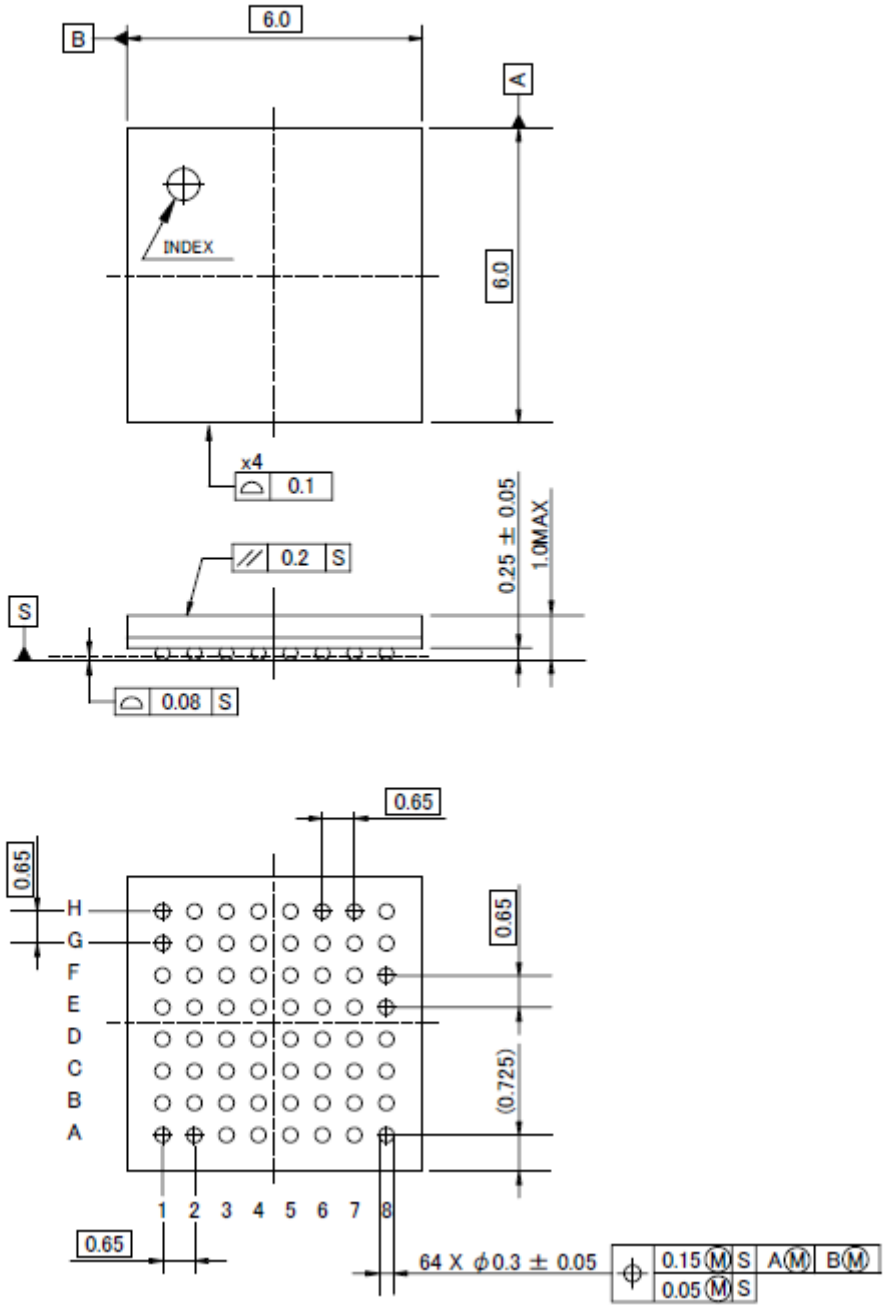
4.4. TC358771XBG BGA49 Pin Count Summary

Table 4.2 TC358771XBG BGA49 Pin Count Summary

Group Name	Pin Count	Notes
DSI-RX IF	14	Include DSI Power & Ground
LVDS-TX IF	16	Include LVDS Power & Ground
I^2C IF	2	-
GPIO	3	-
PWM	1	-
SYSTEM	13	Include Power & Ground
Total Pin Count	**49**	

5. Package

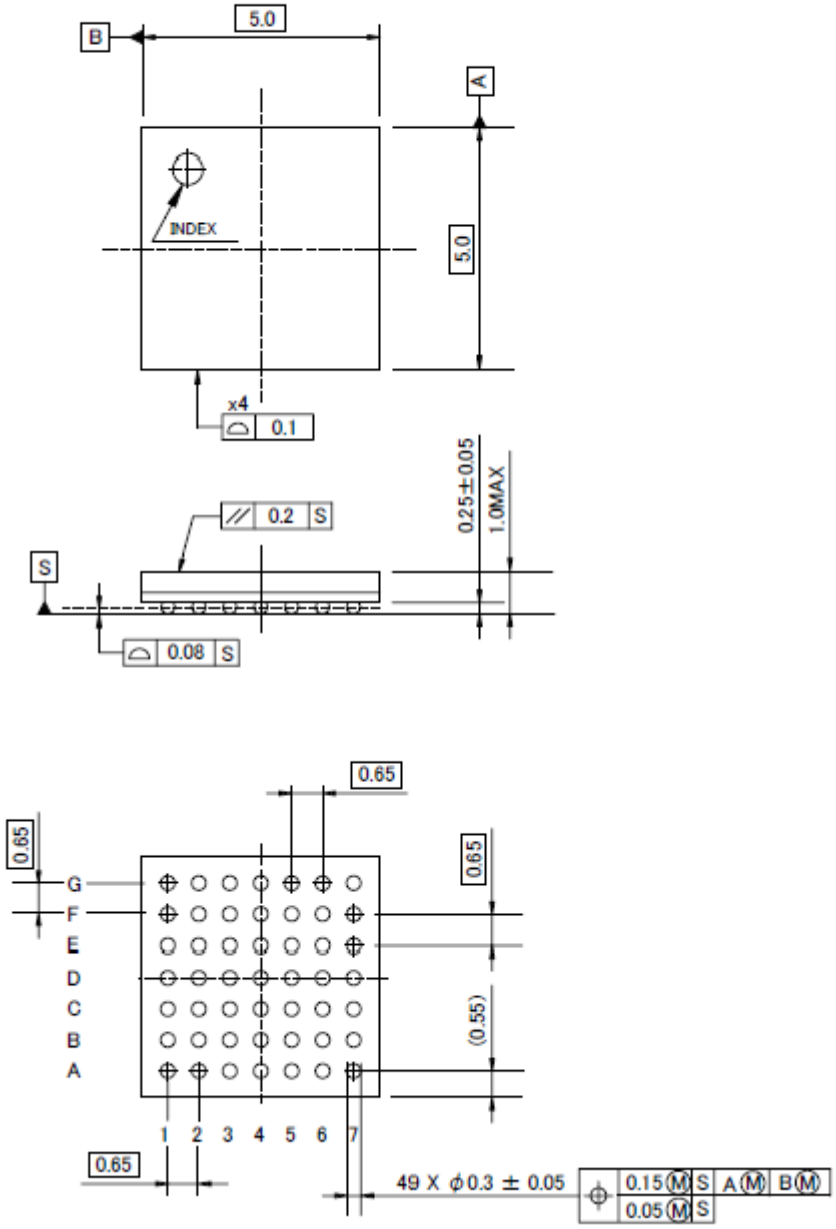
P-VFBGA64-0606-0.65-001 "Unit : mm"



Weight: 47mg (Typ.)

Figure 5.1 P-VFBGA64-0606-0.65-001 (TC358772XBG) Package Drawing

P-VFBGA49-0505-0.65-001 "Unit:mm"



Weight: 31 mg (Typ.)

Figure 5.2 P-VFBGA49-0505-0.65-001 (TC358771XBG) Package Drawing

Table 5.1 Information Summary

	TC358772XBG Package	TC358771XBG Package
Package Type	VFBGA	VFBGA
Ball Diameter	0.3 mm	0.3mm
Ball Pitch	0.65 mm	0.65 mm
Body Size	6 mm × 6 mm	5 mm × 5 mm
Thickness	1 mm	1 mm

6. Electrical characteristics

6.1. Absolute Maximum Ratings

All voltage values, except differential I/O bus voltages, are with respect to network ground terminal.

Table 6.1 Absolute Maximum Ratings

Parameter	Symbol	Rating	Unit
Supply voltage (1.8V – Digital IO)	VDDIO	-0.3 to +3.9	V
Supply voltage (1.2V – Digital Core)	VDDC	-0.3 to +1.8	V
Supply voltage (1.2V – MIPI DSI PHY)	VDD_MIPI	-0.3 to +1.8	V
Supply voltage (1.8V – LVDS PHY)	VDD_LVDS1_18, VDD_LVDS2_18	-0.3 to +3.9	V
Supply voltage (1.2V – LVDS PHY)	VDD_LVDS1_12 VDD_LVDS2_12	-0.3 to +1.8	V
Input voltage (DSI I/O)	V_{IN_DSI}	-0.3 to VDD_MIPI+0.3	V
Output voltage (DSI I/O)	V_{OUT_DSI}	-0.3 to VDD_MIPI+0.3	V
Input voltage (Digital IO)	V_{IN_IO}	-0.3 to VDDIO+0.3	V
Output voltage (Digital IO)	V_{OUT_IO}	-0.3 to VDDIO+0.3	V
Output voltage (LVDS Driver)	V_{OUT_LVDS}	-0.3 to VDD_LVDS_18+0.3	V
Input current	Iin	-10 to +10	mA
Storage temperature	T_{stg}	-40 to +125	°C

6.2. Operating Conditions

Table 6.2 Operating Conditions

Parameter	Symbol	Min	Typ.	Max	Unit
Supply voltage (1.8V – Digital IO)	VDDIO	1.7	1.8	1.9	V
Supply voltage (3.3V – Digital IO)	VDDIO	3.0	3.3	3.6	V
Supply voltage (1.2V – Digital Core)	VDDC	1.1	1.2	1.3	V
Supply voltage (1.2V – LVDS PHY)	VDD_LVDS_12	1.1	1.2	1.3	V
Supply voltage (1.8V – LVDS PHY)	VDD_LVDS_18	1.7	1.8	1.9	V
Supply voltage (1.2V – MIPI-DSI PHY)	VDD_MIPI	1.1	1.2	1.3	V
Operating internal frequency	fopr	-	-	150	MHz
Operating temperature (ambient temperature with voltage applied)	T_a	-30	+25	+85	°C

7. Revision History

Table 7.1 Revision History

Revision	Date	Description
0.31	2014-04-21	Newly released
0.312	2016-04-01	Package's weight is rounding up digits after the decimal point to form an integer.
1.0	2017-10-31	Added note to Table 4.1 and Table 4.2. Changed header, footer and the last page. Changed corporate name.

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